

SoltexFill ETPR Telecom Cable Filling Compound

Description

Soltexfill ETPR is a low viscosity cable filling compound especially designed to protect against moisture ingress in various copper telecom cable designs. Soltexfill ETPR is formulated using high quality hydrocarbons base fluids and gelling agents with good compatibility with other cable construction materials. Soltexfill ETPR is designed for easier removal by craftspeople for splicing and termination.

Properties

TYPICAL PROPERTIES	Method	Units	Typical
Appearance			White, ductile, solid
Color, molten	ASTM D 1500		L0.5
Viscosity, 110°C	ASTM D 3236	cPs	57.4
Viscosity, 130°C	ASTM D 3236	cPs	35.5
Viscosity, 150°C	ASTM D 3236	cPs	23.4
Density @ 20°C	ASTM D 792	g/cm ³	0.869
Melt Drop Point	ASTM D 127	°C	95.4
Cone Penetration @ 25°C	ASTM D 937	0.1 mm	75.0
Flash Point, COC	ASTM D 92	°C	243
Neutralization Number	ASTM D 974	mgKOH/g	<0.05
Oxidation Induction Time, 190°C	ASTM D 3895	minutes	>15
Slump Test, 80°C	Tombstone		Pass

Packaging

Available in bulk tank trucks, iso-containers, totes & drums

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